



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 09/388,031

Filed: September 1, 1999

For: METALLIZATION STRUCTURES FOR SEMICONDUCTOR DEVICE INTERCONNECTS, METHODS FOR MAKING SAME, AND

SEMICONDUCTOR DEVICES

INCLUDING SAME

Confirmation No.: 3303

Examiner: E. Lee

Group Art Unit: 2815

Attorney Docket No.: 2269-3442.2US

(96-0428.00/US)

Notice of Allowance Mailed:

November 25, 2005

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: <u>EL995990316US</u>

Date of Deposit with USPS: February 23, 2006

Person making Deposit: Timothy Palfreyman

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Abstract appear on page 13 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 14 of this paper.

Remarks begin on page 24 of this paper.